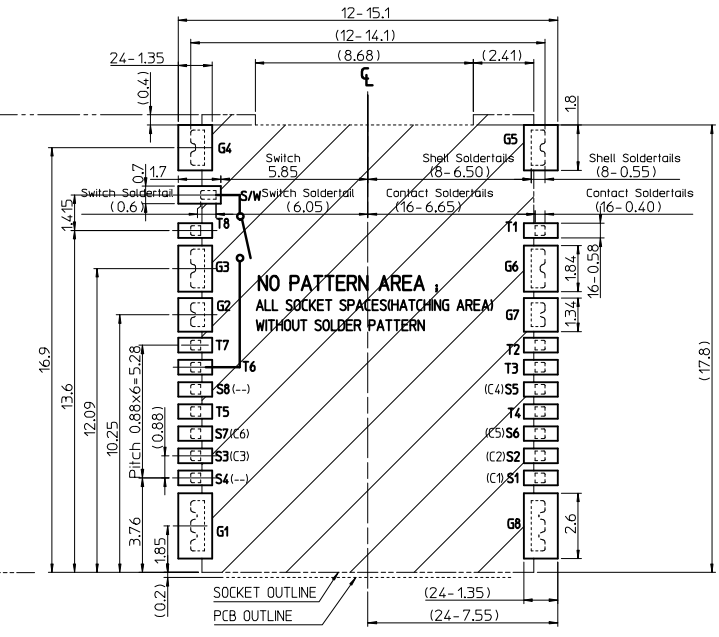
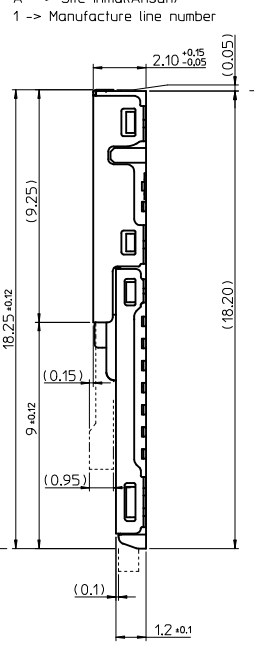
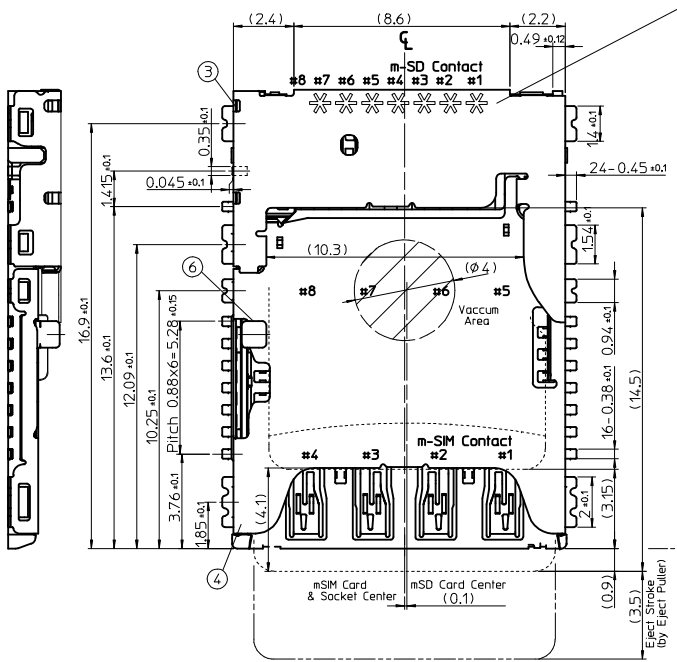


-DATE CODE-  
 example: 12B15A1  
 M -> Molex initial  
 2 -> Year(2012)  
 B -> Month(November) 1, ..., A, B, C  
 15 -> Date(15th)  
 A -> Site initial(Ansan)  
 1 -> Manufacture line number

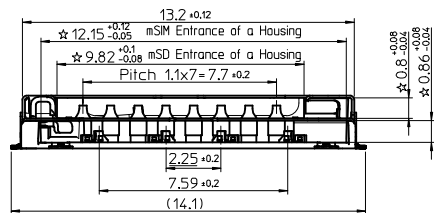
[ microSIM CARD PIN-MAP ]  
 \* See Sheet3 For Detail (8P Vs 6P)

8P	6P	DESCRIPTION
S1	C1	Vcc(Supply V)
S2	C2	RST(Reset)
S3	C3	CLK(Clock)
S4	--	Reserved
S5	C4	GND
S6	C5	Vpp(Program V)
S7	C6	I/O
S8	--	Reserved
G1-G8	GND	



[ microSD CARD PIN-MAP ]

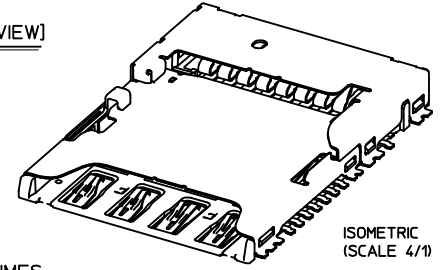
PIN NO.	DESCRIPTION
T1	DAT2
T2	CD/DAT3 <sup>2</sup>
T3	CMD
T4	Vcc
T5	CLK
T6	Vss (GND)
T7	DAT0
T8	DAT1
S/W	CARD DETECTOR



NOTES

1. MATERIALS: SEE TABLE
2. FINISHES: SEE TABLE
3. MATES WITH
  - UPPER: microSD Card
  - LOWER: Micro SIM(UICC) Card
4. PRODUCT SPECIFICATIONS: PS-104642-001
5. PACKING SPECIFICATIONS: SPK-104642-002
6. COPLANARITY OF SOLDER TAILS: 0.08mm MAX. BEFORE & AFTER 250°C REFLOW 2TIMES
7. REFERENCE CARD DIMENSIONS ARE WITH STANDARD DIMENSION CARD
8. CUSTOMER'S CTF DIMENSION(\*) IS EQUAL TO MOLEX MAJOR QUALITY SYMBOL(▼)

RECOMMENDED PCB LAYOUT [FRONT VIEW]  
 (TOLERANCE : ±0.05)



[ Circuit diagram for Detection Switch of microSD card ]

Card insertion condition	Card detect switch	Circuit
Without Card	Open	
Card insertion	Close	

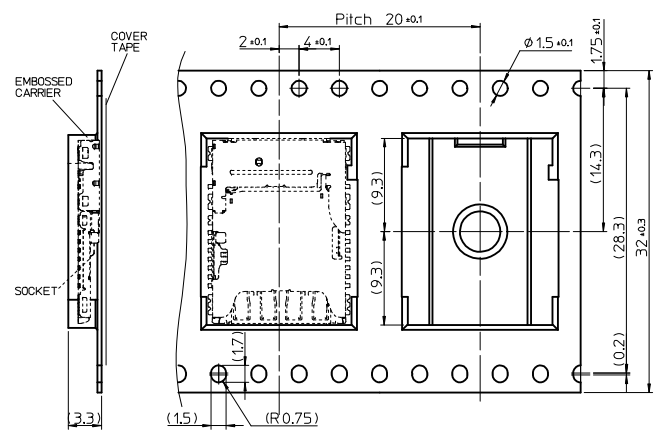
NO.	PARTS NAME	MATERIALS	FINISHES
1	CONTACT TERMINAL(16P)	COPPER ALLOY	CONTACT mSIM : GOLD 0.054μm MIN. OVER Pd-Ni 0.34μm MIN. CONTACT mSD : GOLD 0.054μm MIN Pd-Ni 0.24μm MIN. SWITCH : GOLD 0.14μm MIN. (Pd-Ni IS PALLADIUM NICKEL)SOLDERS : GOLD 0.054μm MIN. BASE : NICKEL 1.274μm MIN.
2	SWITCH TERMINAL	PHOSPHOR BRONZE	
3	microSD SHELL	STAINLESS STEEL	BRIGHT NICKEL 1.274μm MIN.
4	microSIM SHELL	STAINLESS STEEL	BRIGHT NICKEL 1.274μm MIN.
5	HOUSING	LIQUID CRYSTAL POLYMER	NATURAL(IVORY) COLOR, UL94V-0
6	EJECT PULLER	STAINLESS STEEL	NONE

REVISED QUANTITY	2014/12/01	2014/12/01	2014/12/09
EC NO: KOR2015-0070	DRW:NEGI/IM	CHK:KDS/SHU	APPR:YSK/IMO2
QUALITY SYMBOLS	▼=4	▽=0	
DESCRIPTION			
REV	A1		

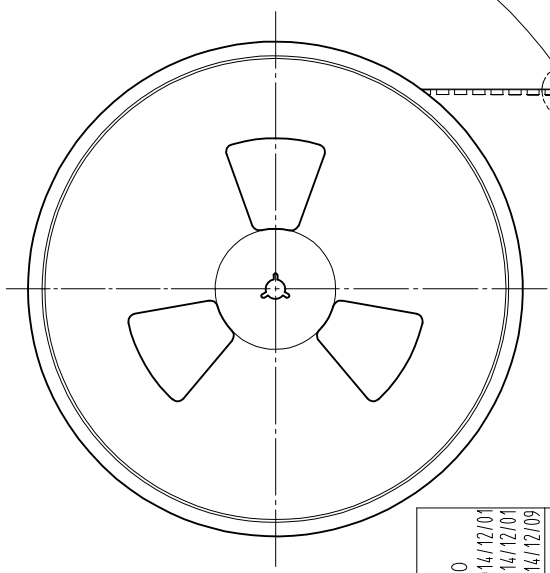
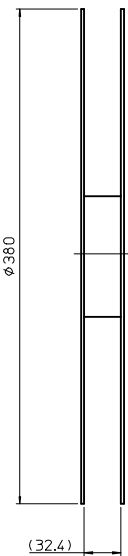
GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
mm INCH	MM ONLY	5/1	METRIC	THIRD ANGLE PROJECTION
4 PLACES ± --- ± ---	DRAWN BY DATE	EGK/IM	2014/04/29	
3 PLACES ± 0.12 ± ---	CHECKED BY DATE			
2 PLACES ± 0.12 ± ---	APPROVED BY DATE		2014/04/29	
1 PLACE ± 0.15 ± ---	APPROVED BY DATE	YSK/IMO2	2014/11/25	
0 PLACE ± 0.15 ± ---	MATERIAL NO.			
ANGULAR ± 1 °	DOCUMENT NO.			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SEE TABLE			
	SIZE A3			

SMD ONLY	104642-1610	1046421610
SOLDER TYPE	PART (ORDER NO.)	MATERIAL NO.
COMBO 2.10H PULLER TYPE MICROSD/MICROSIM 8P/8P WITH S/W		
<b>molex</b>		
SD-104642-001		SHEET NO. 1 OF 3
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

10 9 8 7 6 5 4 3 2 1



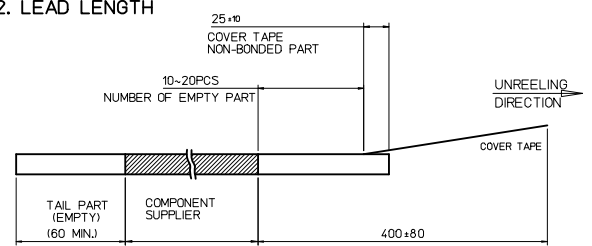
TOP VIEW OF EMBOSSED CARRIER



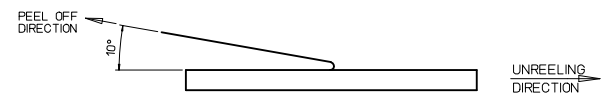
NOTES

1. QUANTITY OF PRODUCTS : 1,500 PCS / 1 REEL

2. LEAD LENGTH



3. PEELING OFF FORCE OF COVER TAPE : 0.1N~0.59N(10.2~60gf)  
(PEELING DIRECTION AS BELOW)  
- PEELING OFF SPEED : 300mm/Min.(Ref.)

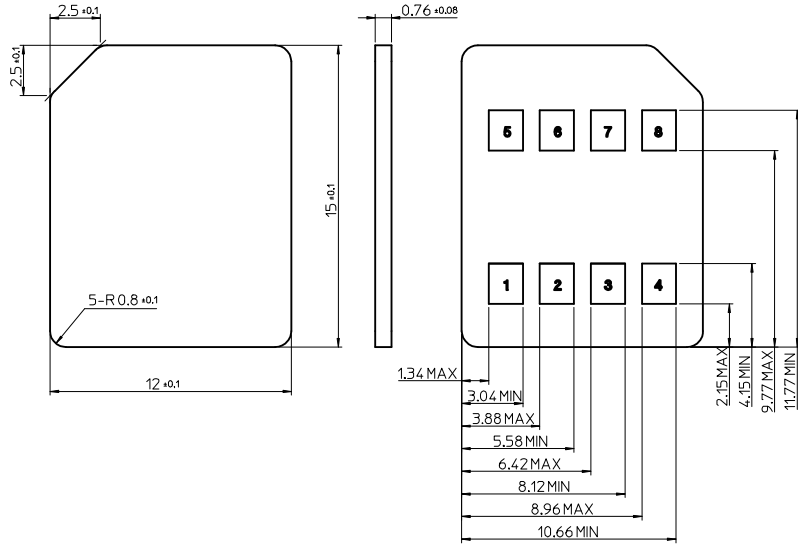


4. MATERIALS OF EMBOSSED CARRIER AND COVER TAPE :  
PET(POLYETHYLEN TEREPHTHALATE)

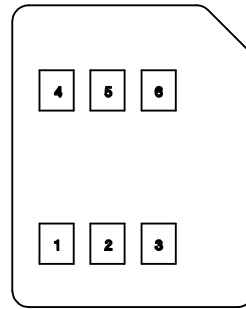
SEE SHEET1 EC NO: KOR2015-0070 DRW:EGKIM 2014/12/01 CHKD:SHCHU 2014/12/01 APPR:YSKIM02 2014/12/09	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE 2/1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		4 PLACES ± --- ± ---	mm INCH	DRAWN BY EGKIM	DATE 2014/04/29	TITLE COMBO 2.10H PULLER TYPE MICROSD/MICROSIM 8P/8P WITH S/W <b>molex</b>			
		3 PLACES ± 0.12 ± ---	2 PLACES ± 0.12 ± ---	CHECKED BY	DATE 2014/04/29				
		1 PLACE ± 0.15 ± ---	0 PLACE ± 0.15 ± ---	APPROVED BY YSKIM02	DATE 2014/11/25	MATERIAL NO. SEE SHEET1	DOCUMENT NO. SD-104642-001	SHEET NO. 2 OF 3	
A1	DESCRIPTION	ANGULAR ± 1 °		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

9 8 7 6 5 4 3 2 1

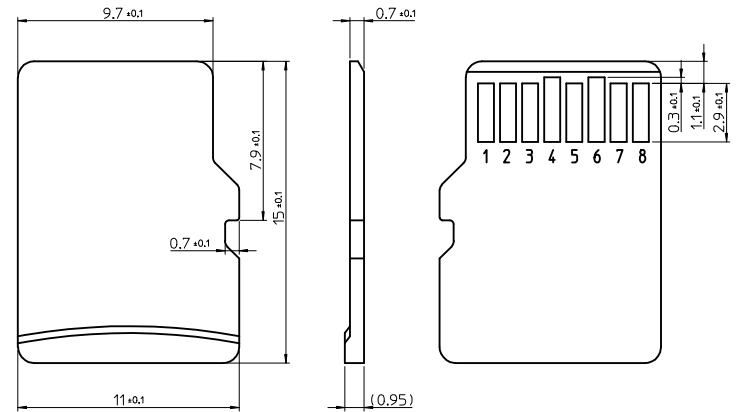
REFERENCE DRAWING



MICRO SIM SPECIFICATION



MICRO SIM 6P



microSD CARD

[Reference Standards]

- microSD Card Addendum Version 3.0 Draft 0.8

- ETSI TS 102 221 V9.1.0, Smart Cards, UICC-Terminal interface, Physical and logical characteristics

SEE SHEET1 IEC NO: KOR2015-0070 DRW:EGKIM 2014/12/01 CHKD:SHCHU 2014/12/01 APPR:YSKIM02 2014/12/09	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE 4/1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
			mm	INCH	DRAWN BY EGKIM	DATE 2014/04/29	TITLE COMBO 2.10H PULLER TYPE MICROSD/MICROSIM 8P/8P WITH S/W <b>molex</b>
		4 PLACES	± ---	± ---	CHECKED BY	DATE 2014/04/29	
		3 PLACES	± 0.12	± ---	APPROVED BY	DATE 2014/11/25	
2 PLACES	± 0.12	± ---	MATERIAL NO. SEE SHEET1	DOCUMENT NO. SD-104642-001			
			1 PLACE	± 0.15	± ---		SHEET NO. 3 OF 3
			0 PLACE	± 0.15	± ---		
			ANGULAR ± 1 °		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				